



US00D395423S

United States Patent [19]

Koyama et al.

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[45] Date of Patent: **Jun. 23, 1998

[54] SEMICONDUCTOR PACKAGE

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[73] Assignee: Sony Corporation, Tokyo, Japan

[**] Term: 14 Years

[21] Appl. No.: 68,117

[22] Filed: Mar. 13, 1997

[51] LOC (6) Cl. 13-03

[52] U.S. Cl. D13/182

[58] Field of Search D13/182; 174/52.2-52.4; 206/710, 719; 257/254, 659, 666, 678-697, 730, 738, 780; 437/183, 217, 220

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Assistant Examiner—Cathron B. Matta
Attorney, Agent, or Firm—Foley & Lardner

[57] CLAIM

The ornamental design for a semiconductor package, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a first embodiment of a semiconductor package showing our new design;

FIG. 2 is a left side elevational view thereof, top plan, bottom plan and right side elevational views are the same image;

FIG. 3 is a front elevational view thereof;

FIG. 4 is a rear elevational view thereof;

FIG. 5 is a perspective view of a second embodiment of a semiconductor package showing our new design;

FIG. 6 is a top plan view of the embodiment of FIG. 5;

FIG. 7 is a left side elevational view of the embodiment of FIG. 5;

FIG. 8 is a front elevational view of the embodiment of FIG. 5;

FIG. 9 is a bottom plan view of the embodiment of FIG. 5;

FIG. 10 is a right side elevational view of the embodiment of FIG. 5;

FIG. 11 is a rear elevational view of the embodiment of FIG. 5;

FIG. 12 is a perspective view of a third embodiment of a semiconductor package showing our new design;

FIG. 13 is a top plan view of the embodiment of FIG. 12;

FIG. 14 is a left side elevational view of the embodiment of FIG. 12;

FIG. 15 is a front elevational view of the embodiment of FIG. 12;

FIG. 16 is a bottom plan view of the embodiment of FIG. 12;

FIG. 17 is a right side elevational view of the embodiment of FIG. 12; and,

FIG. 18 is a rear elevational view of the embodiment of FIG. 12.

1 Claim, 8 Drawing Sheets

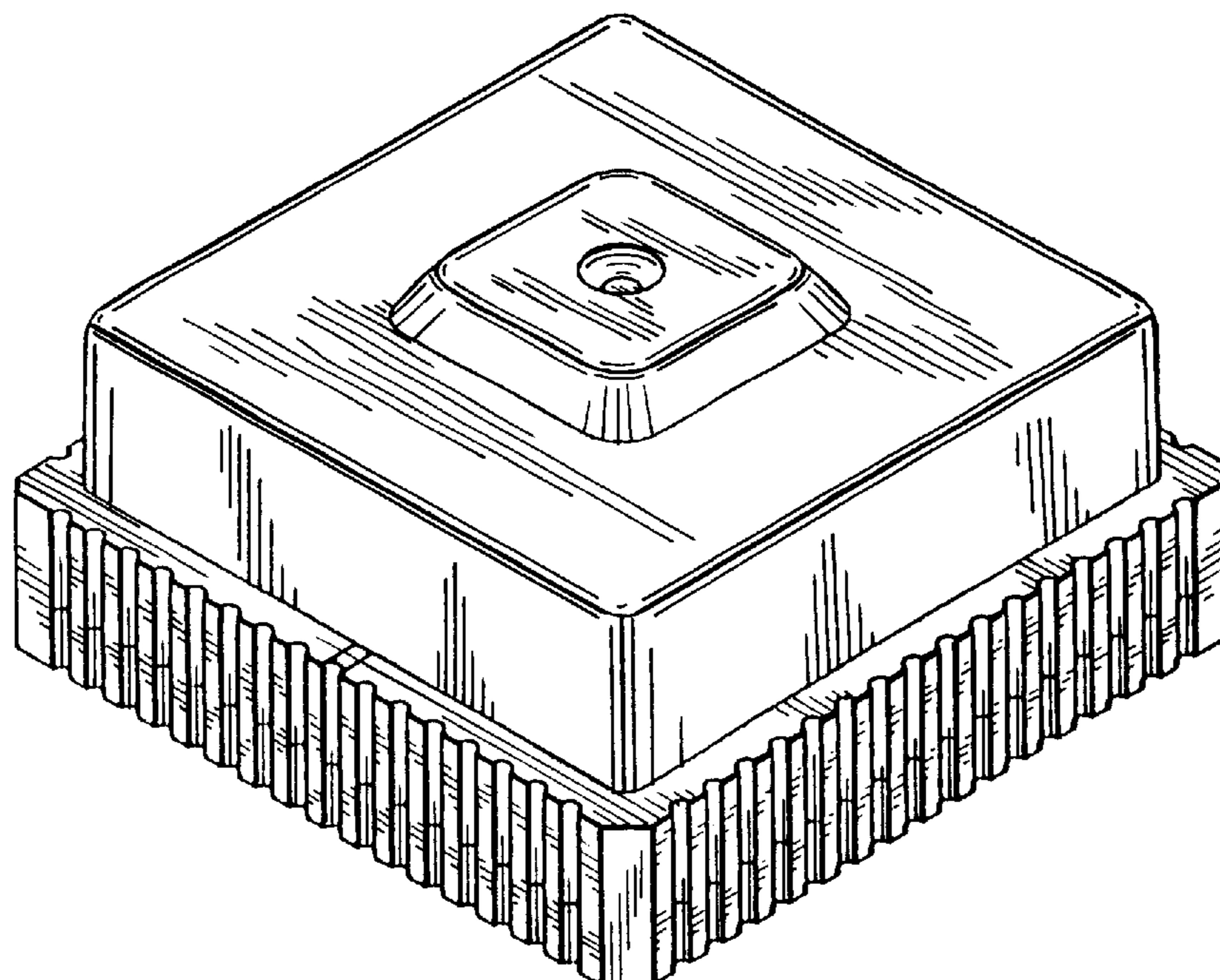


FIG. 1

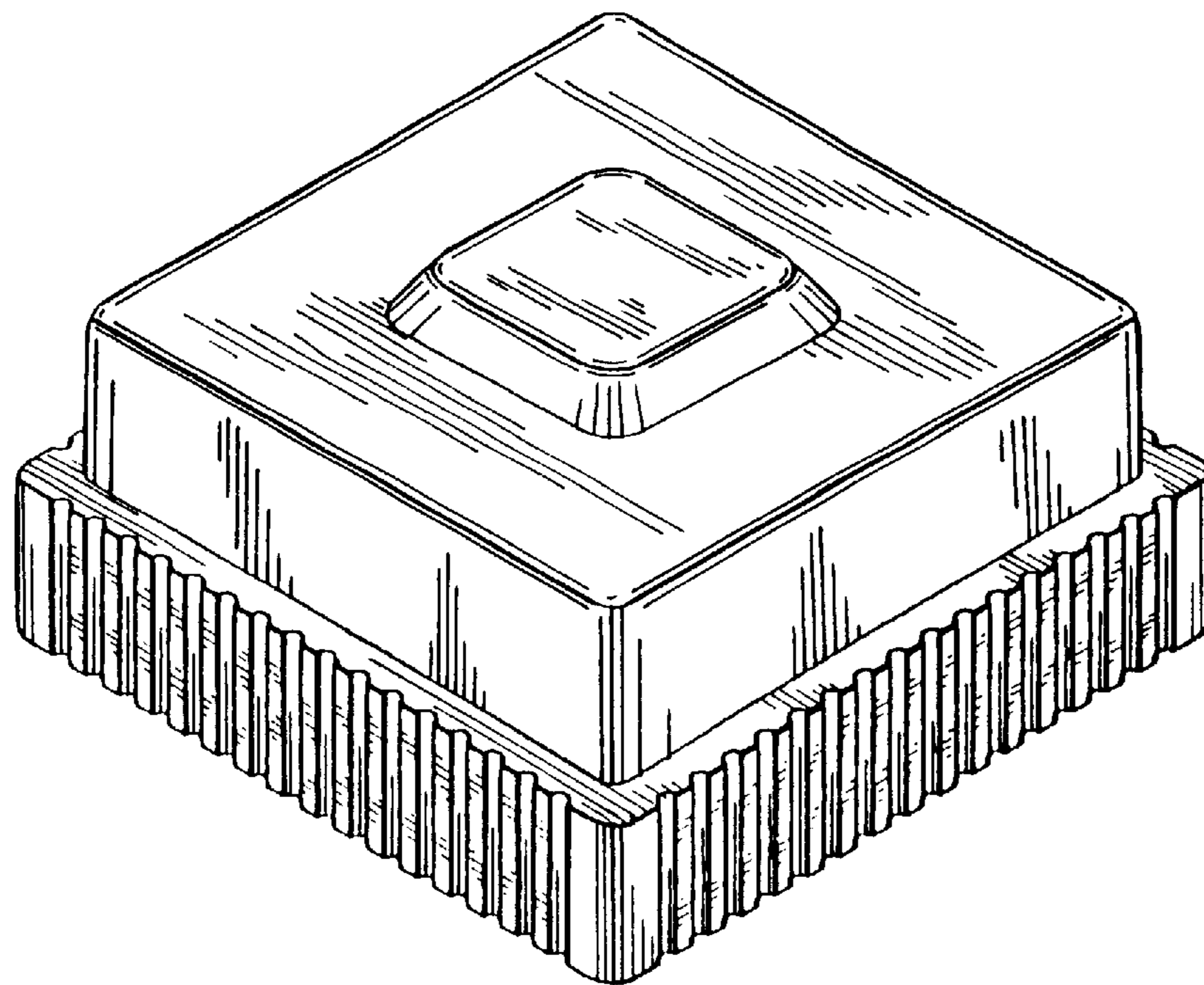


FIG. 2

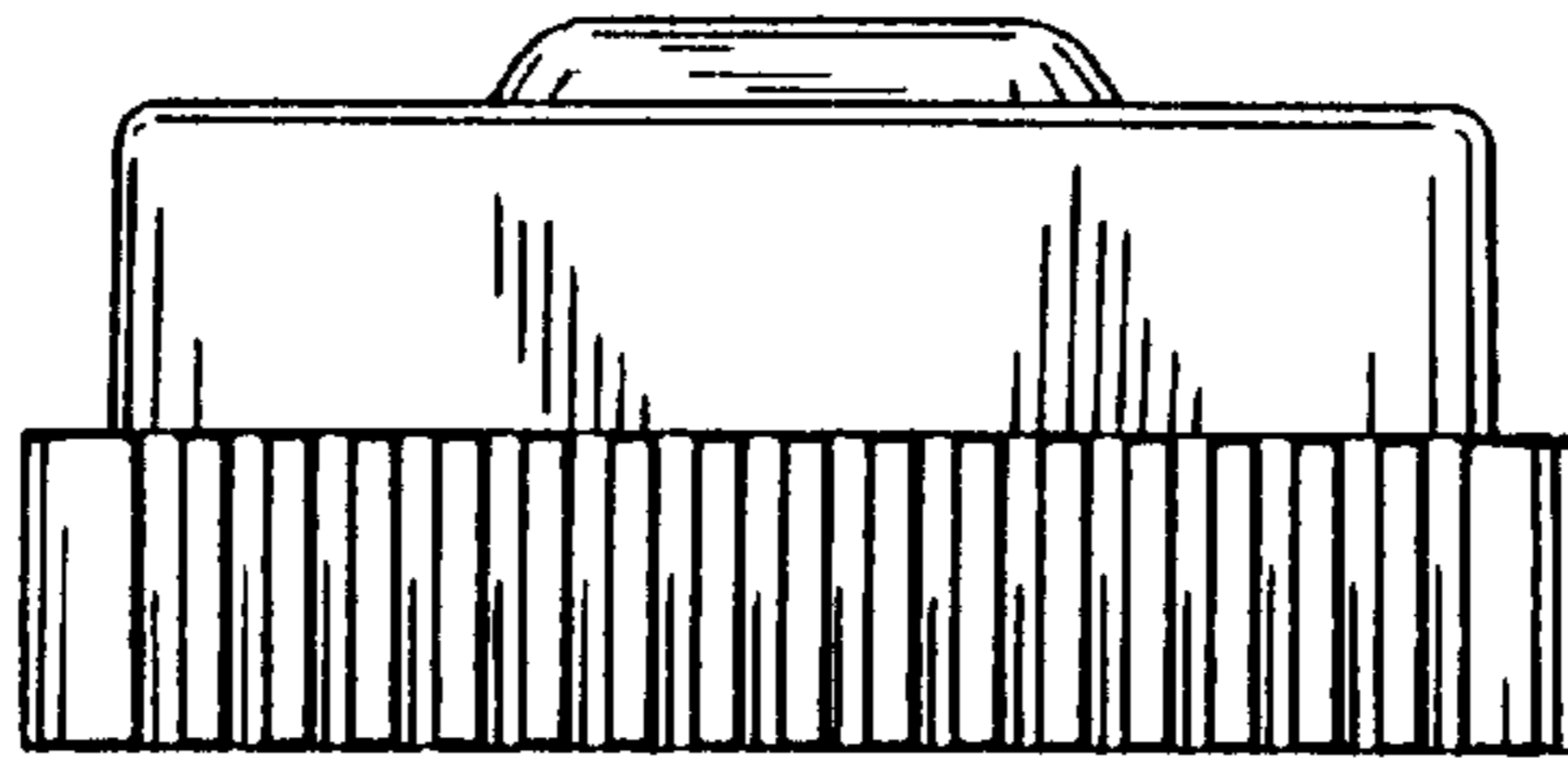


FIG. 3

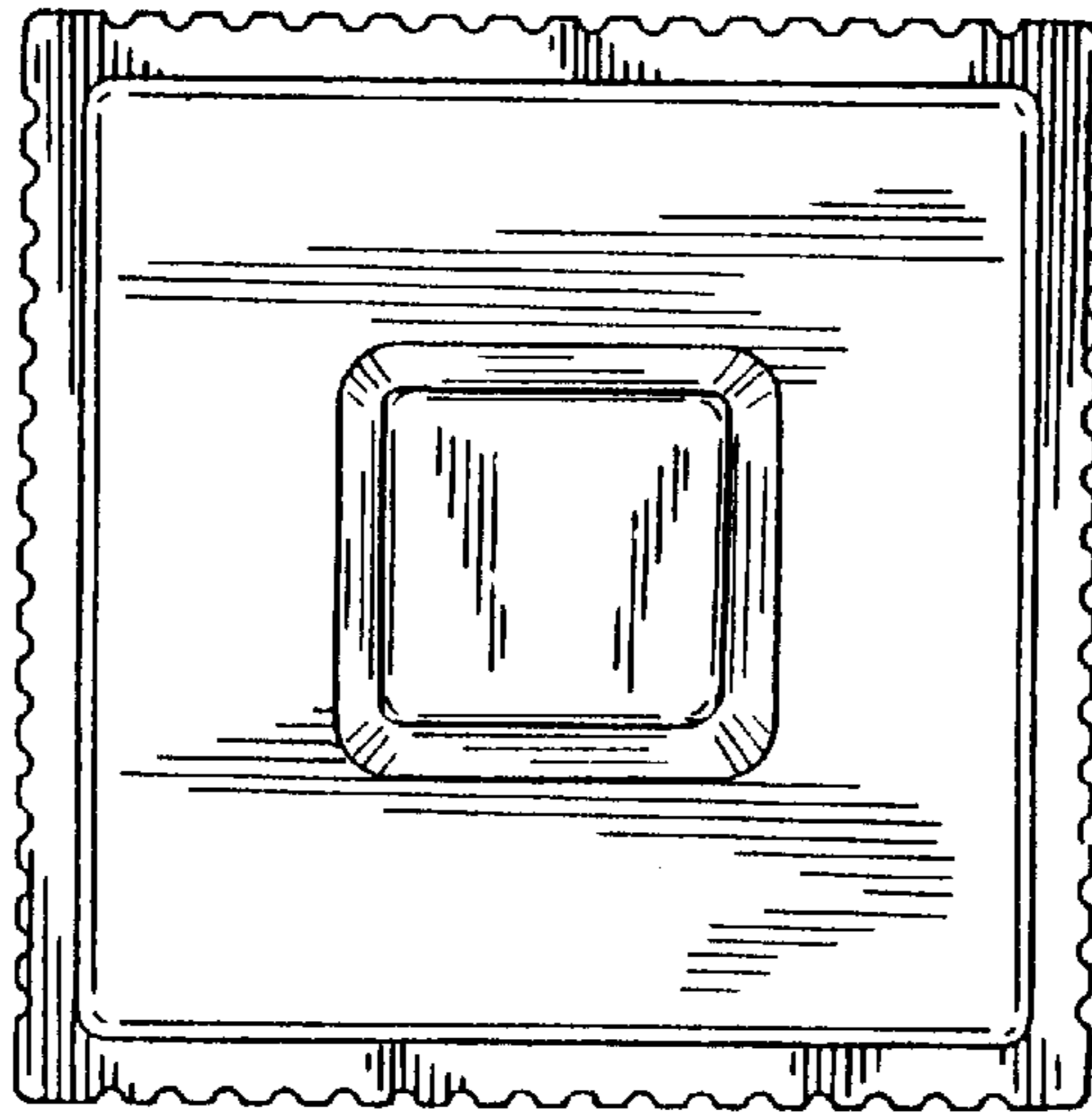


FIG. 4

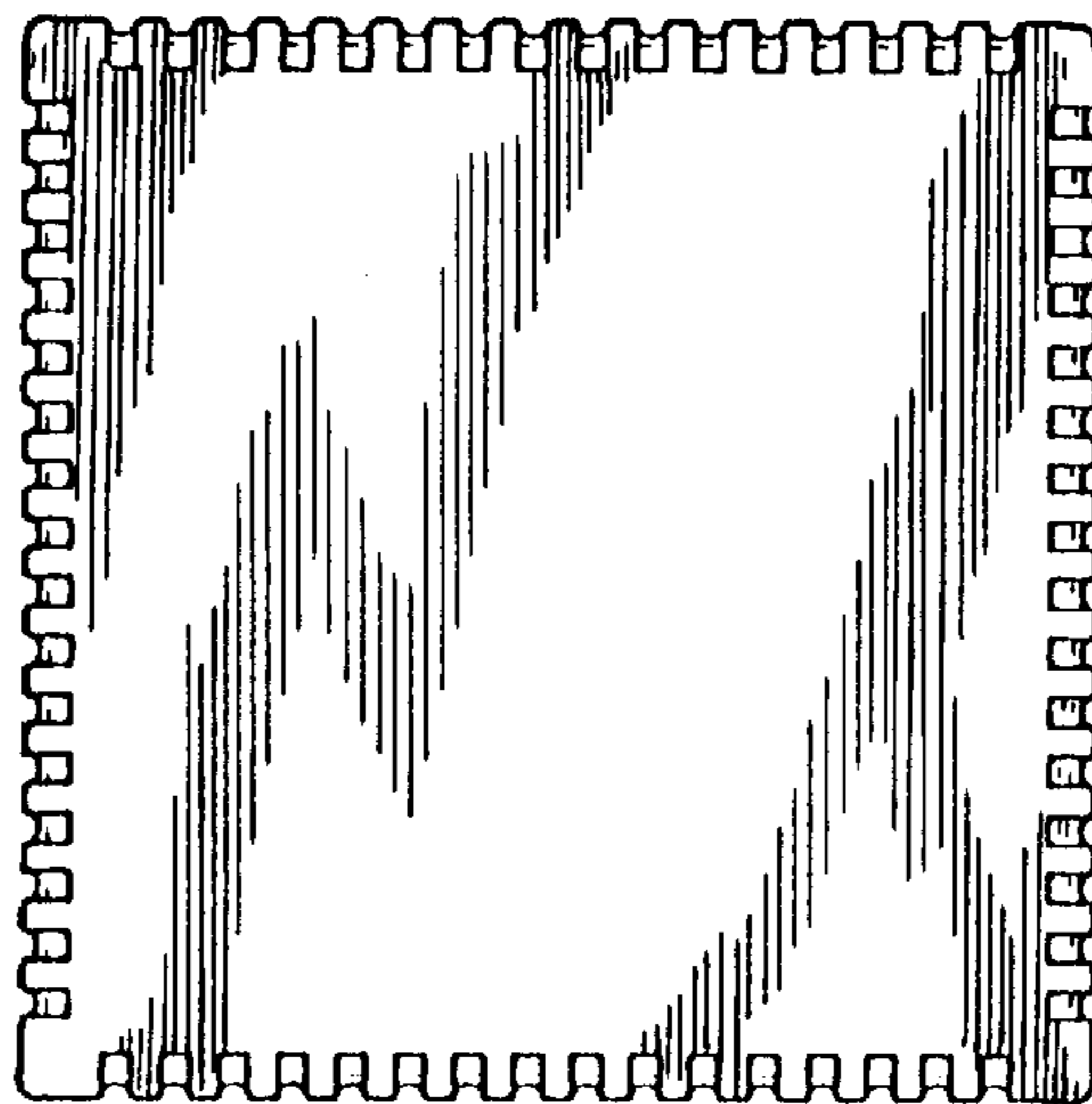


FIG. 5

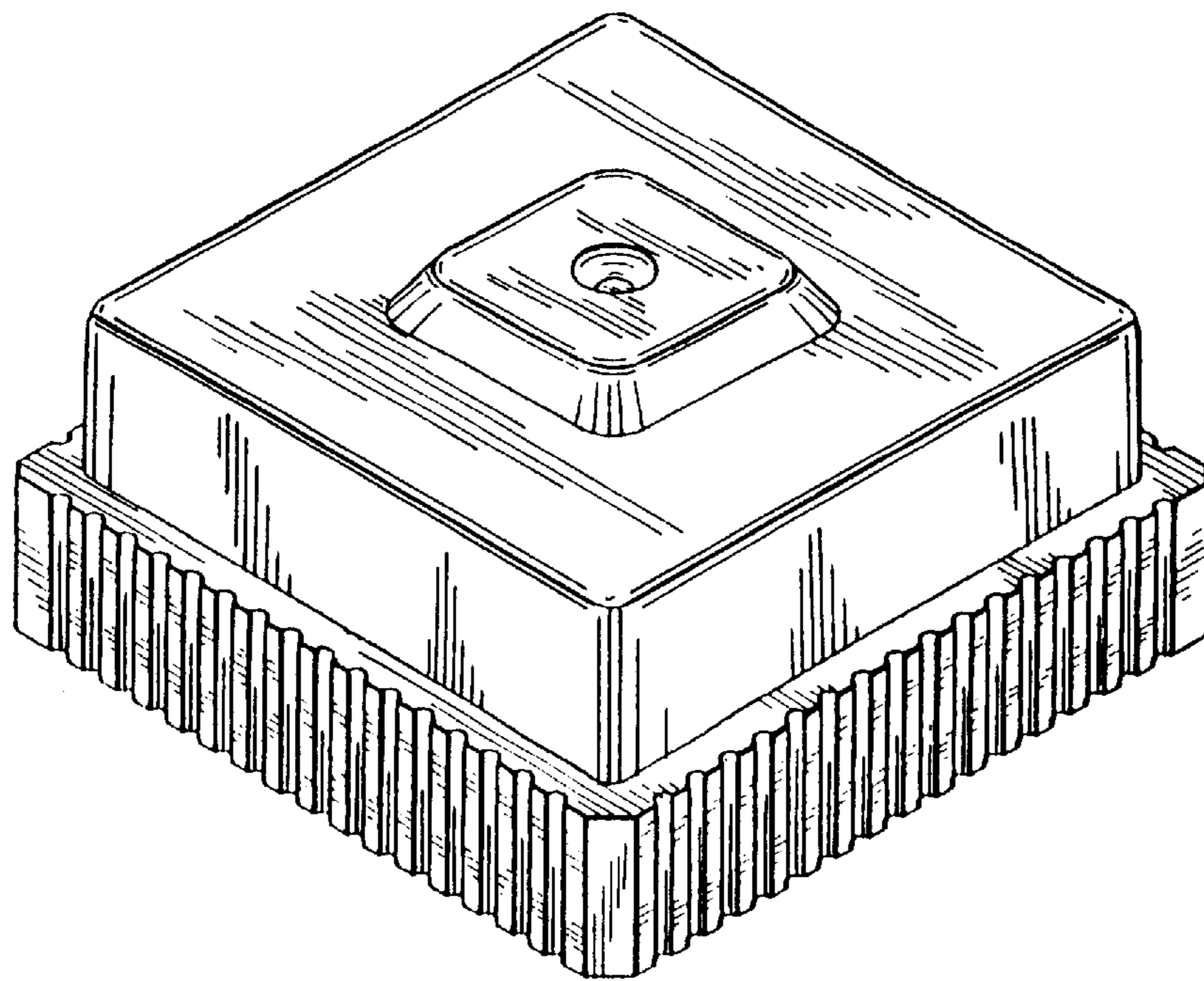


FIG. 6

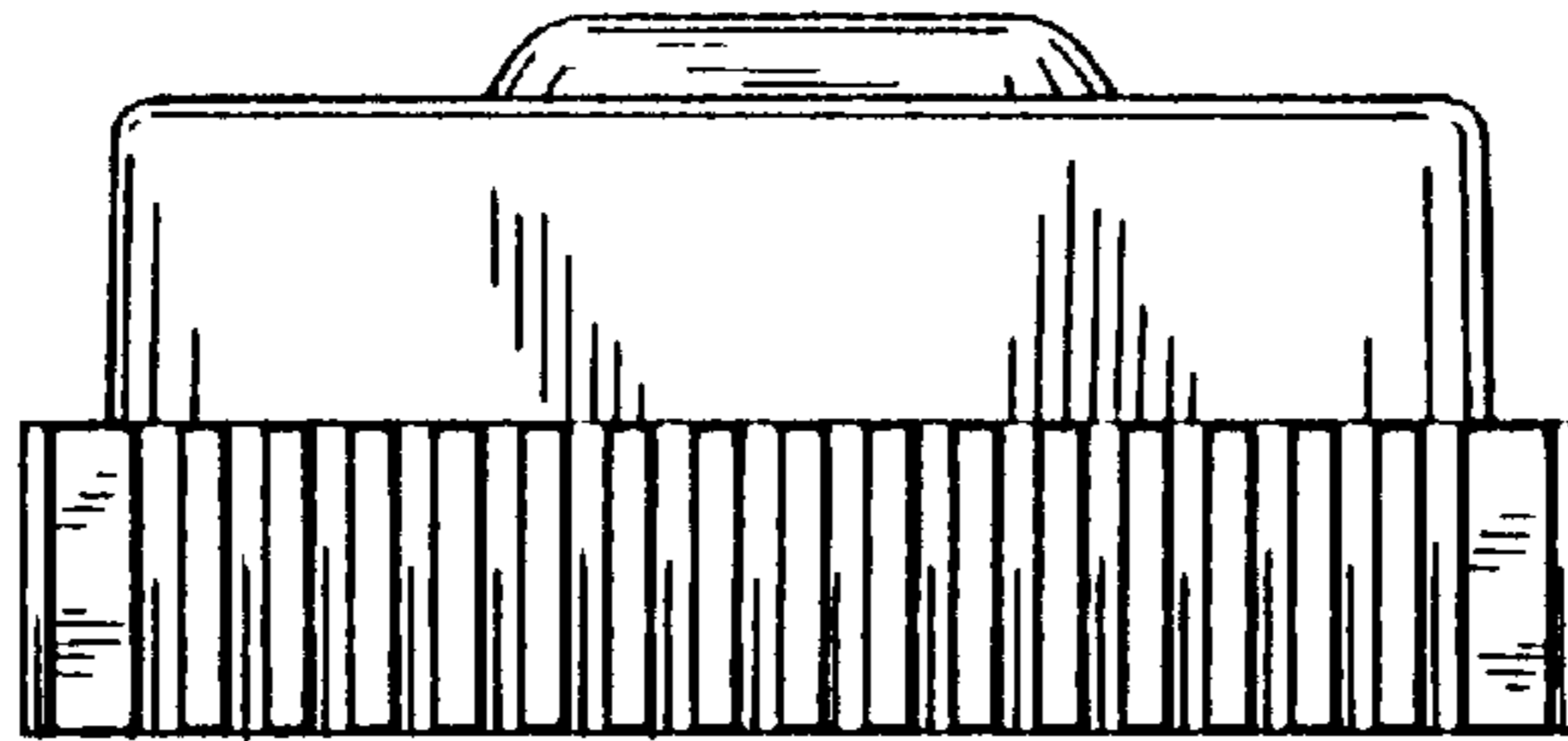


FIG. 8

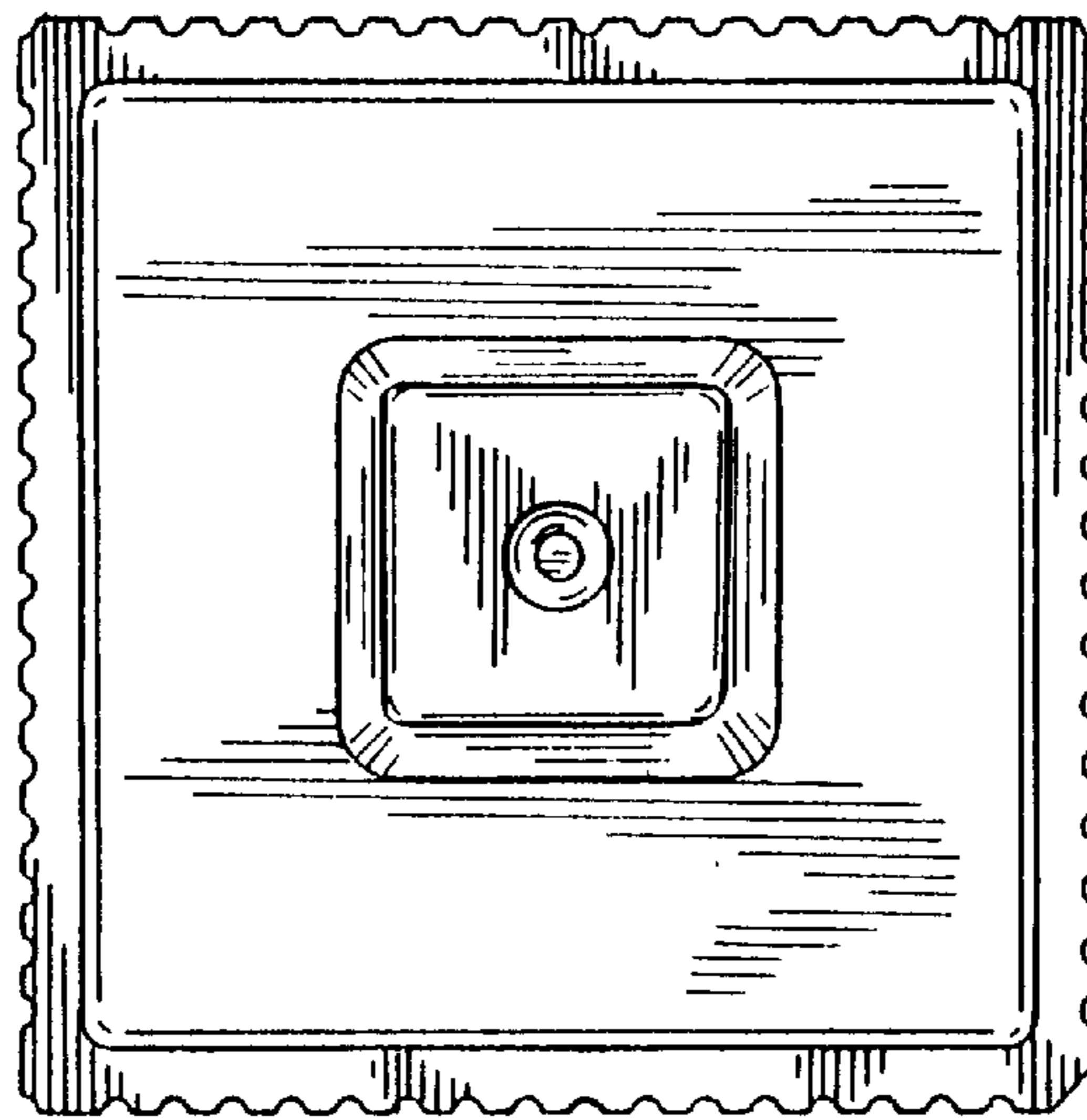


FIG. 9

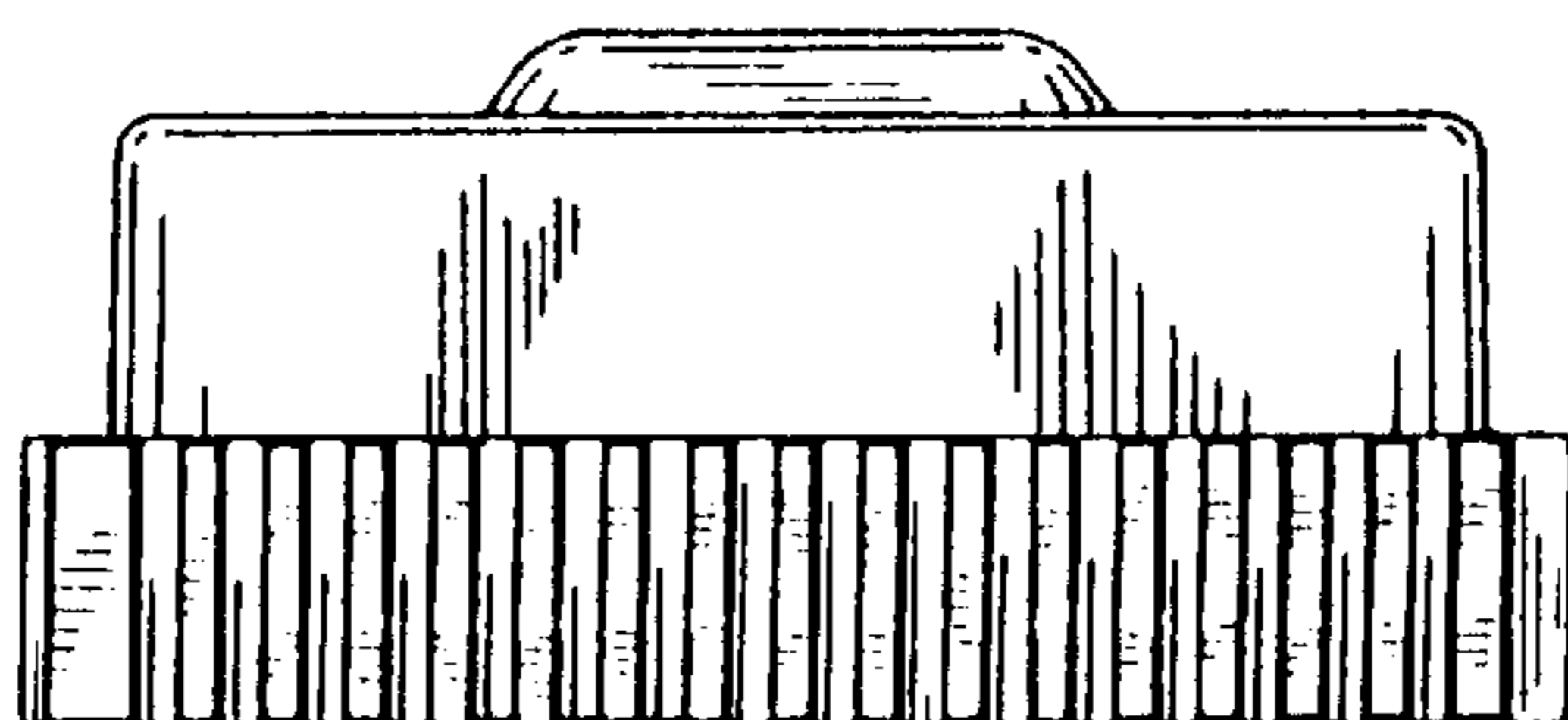


FIG. 7

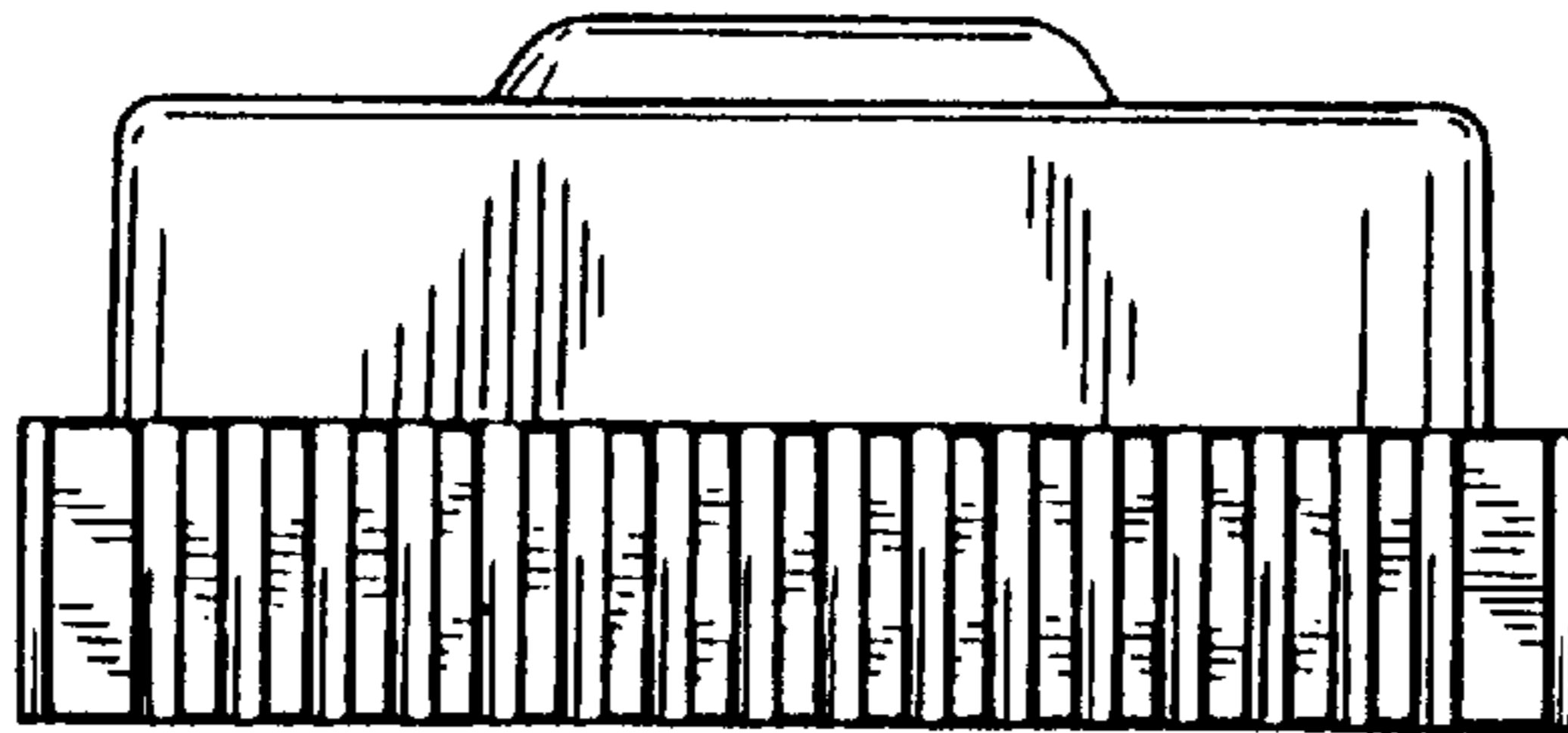


FIG. 11

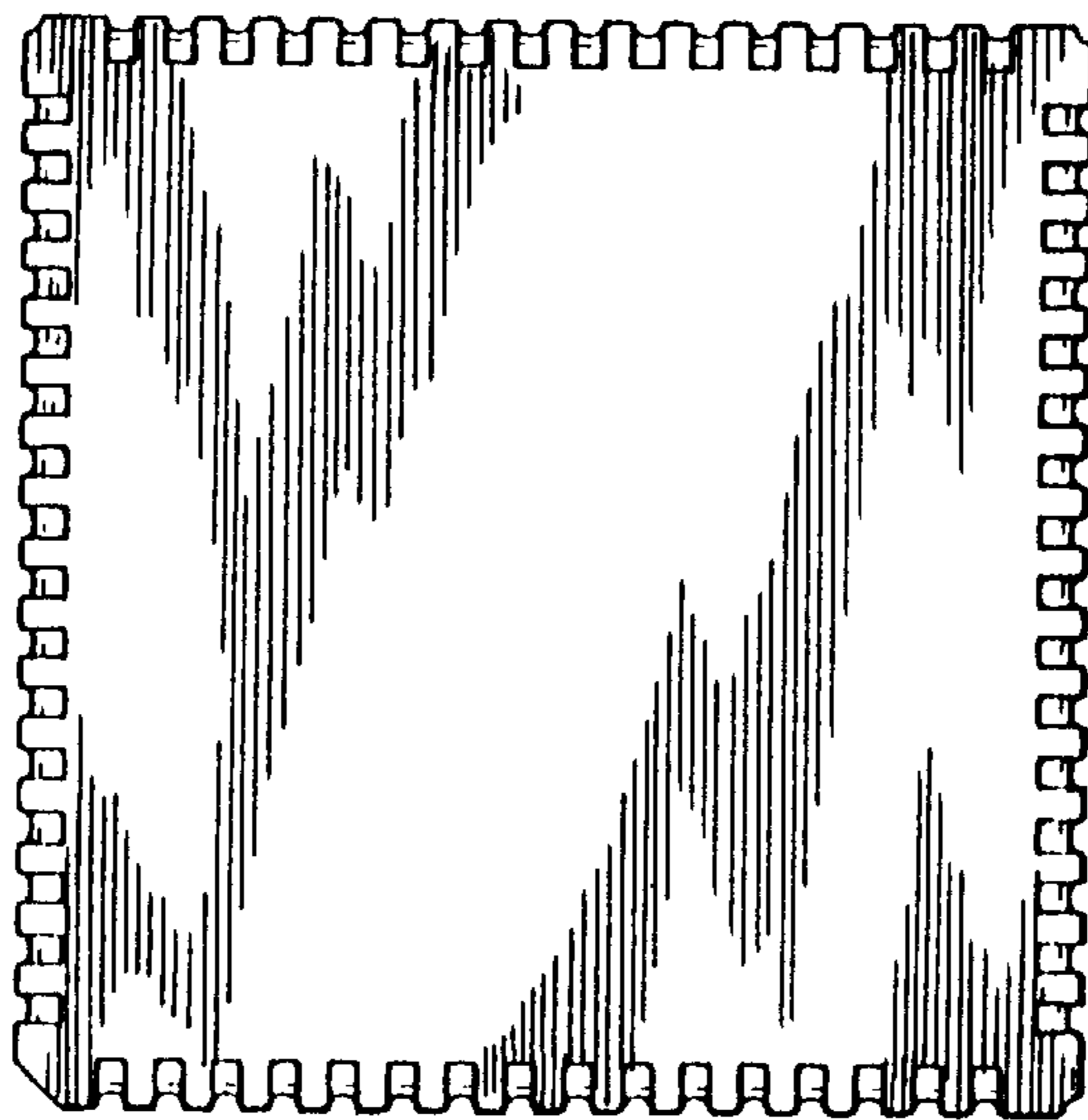


FIG. 10

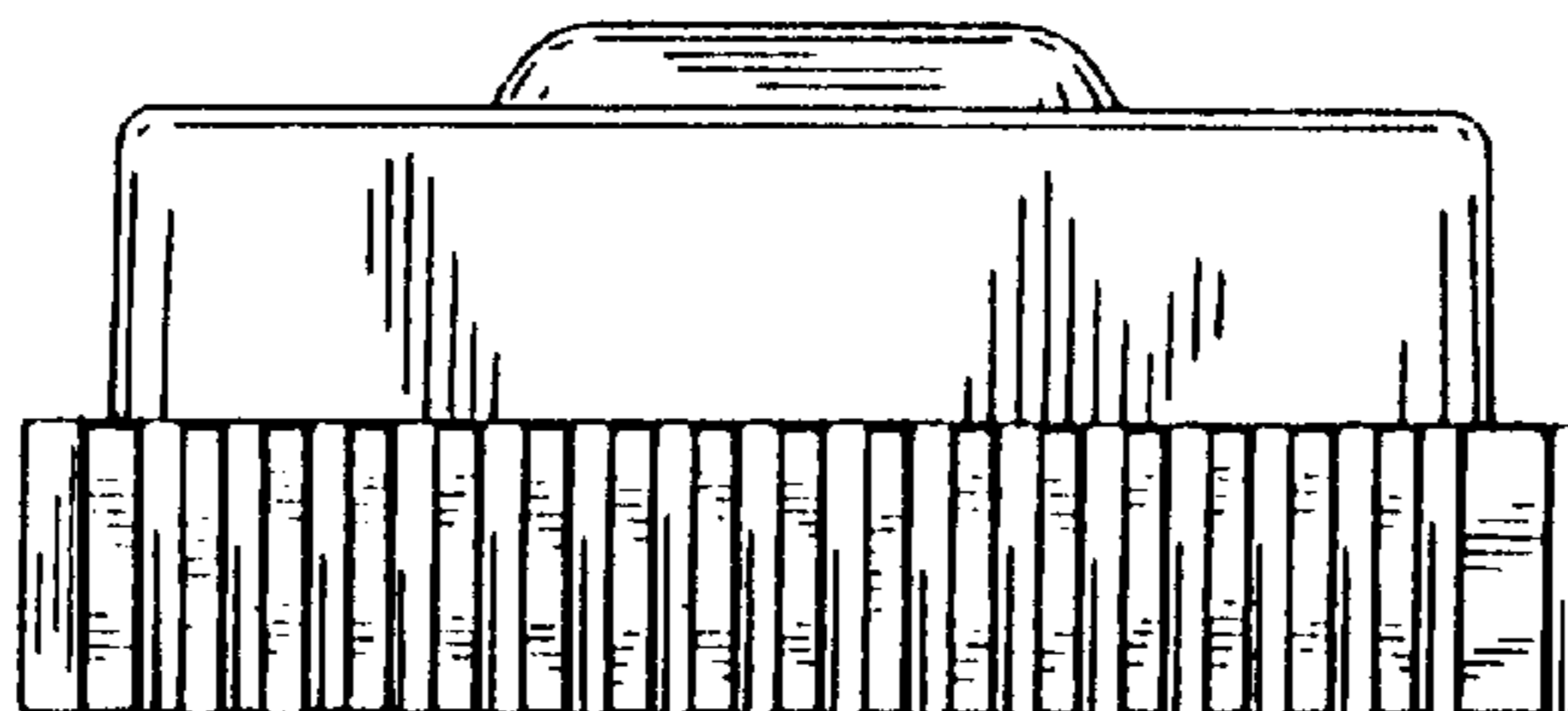


FIG. 12

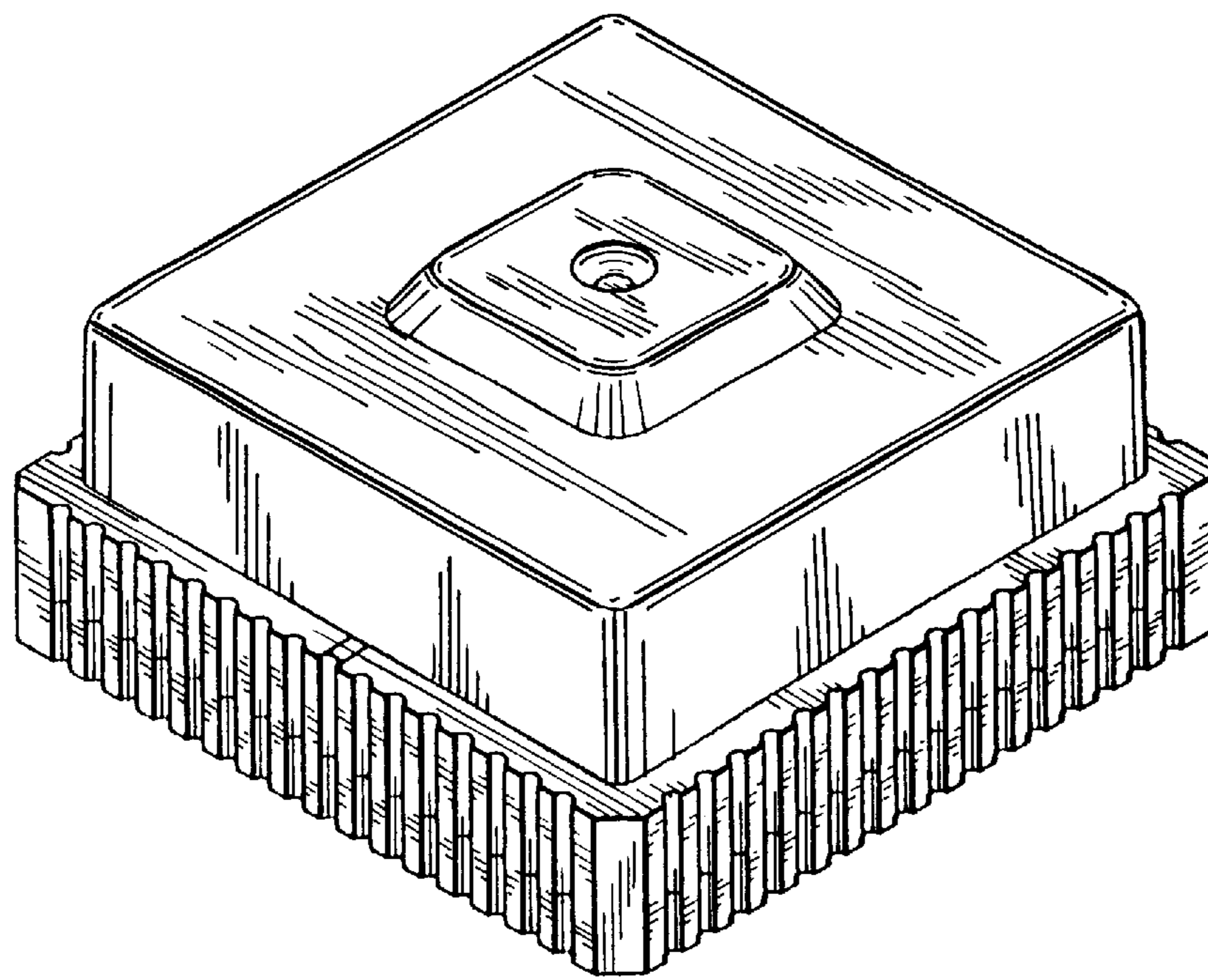


FIG. 13

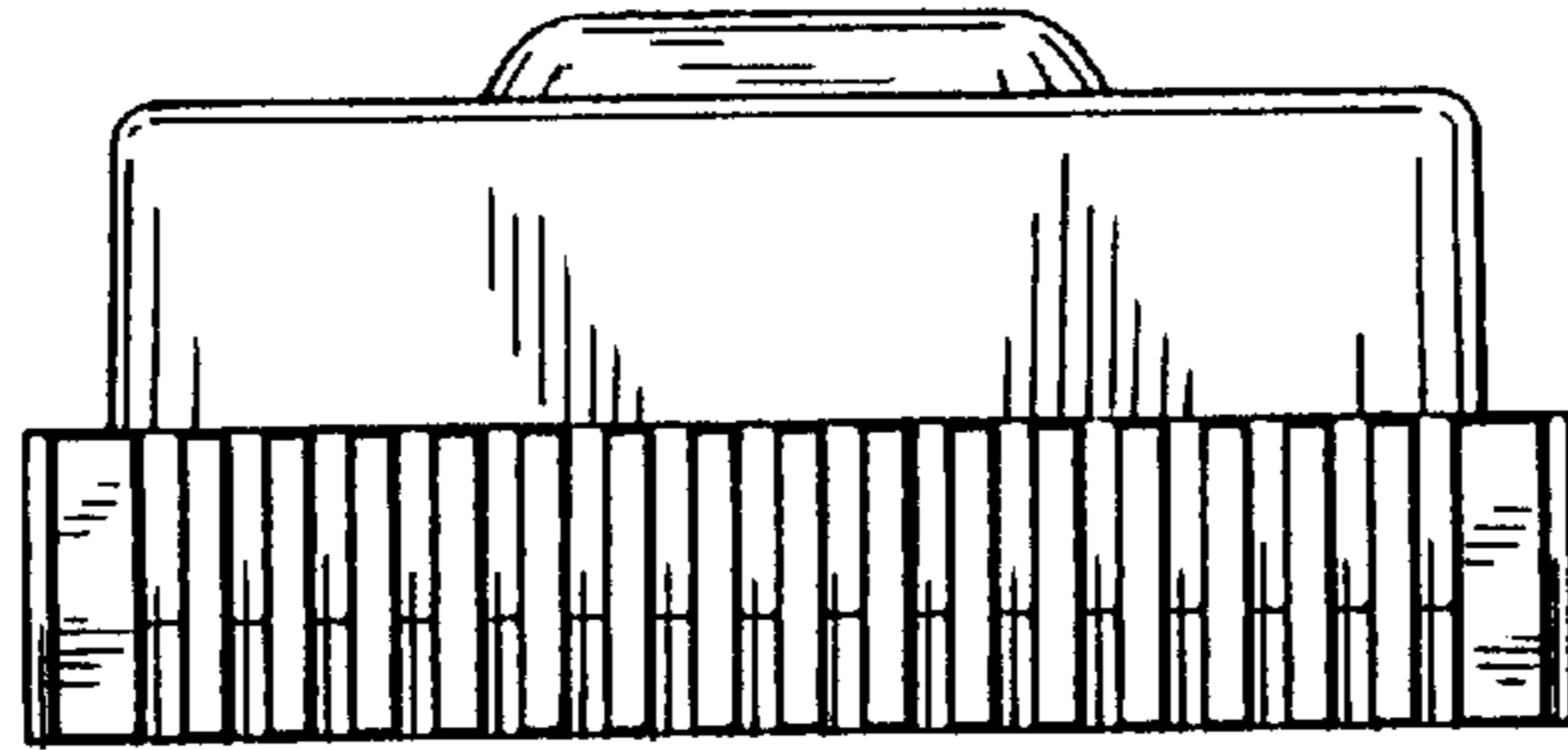


FIG. 15

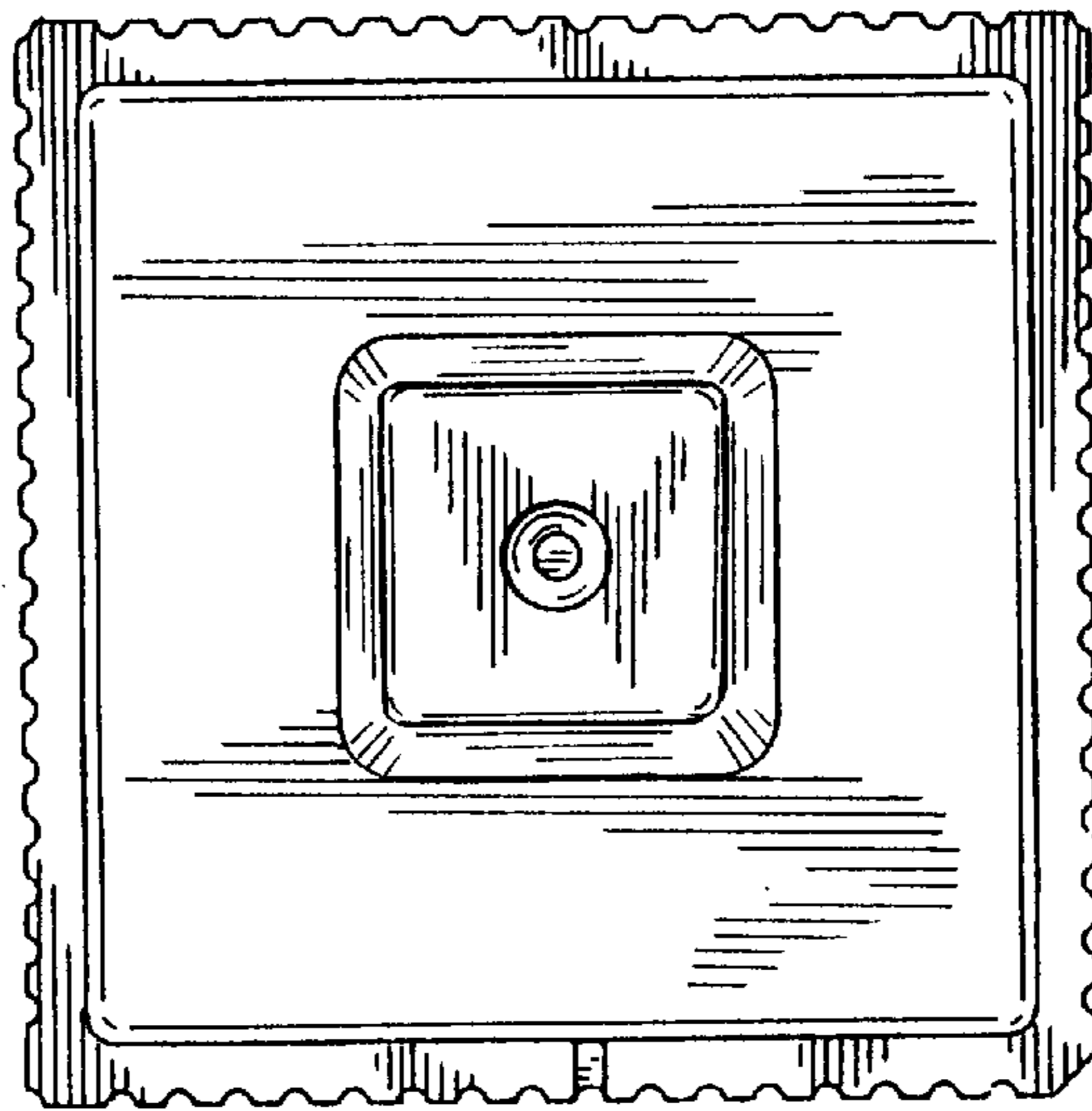


FIG. 16

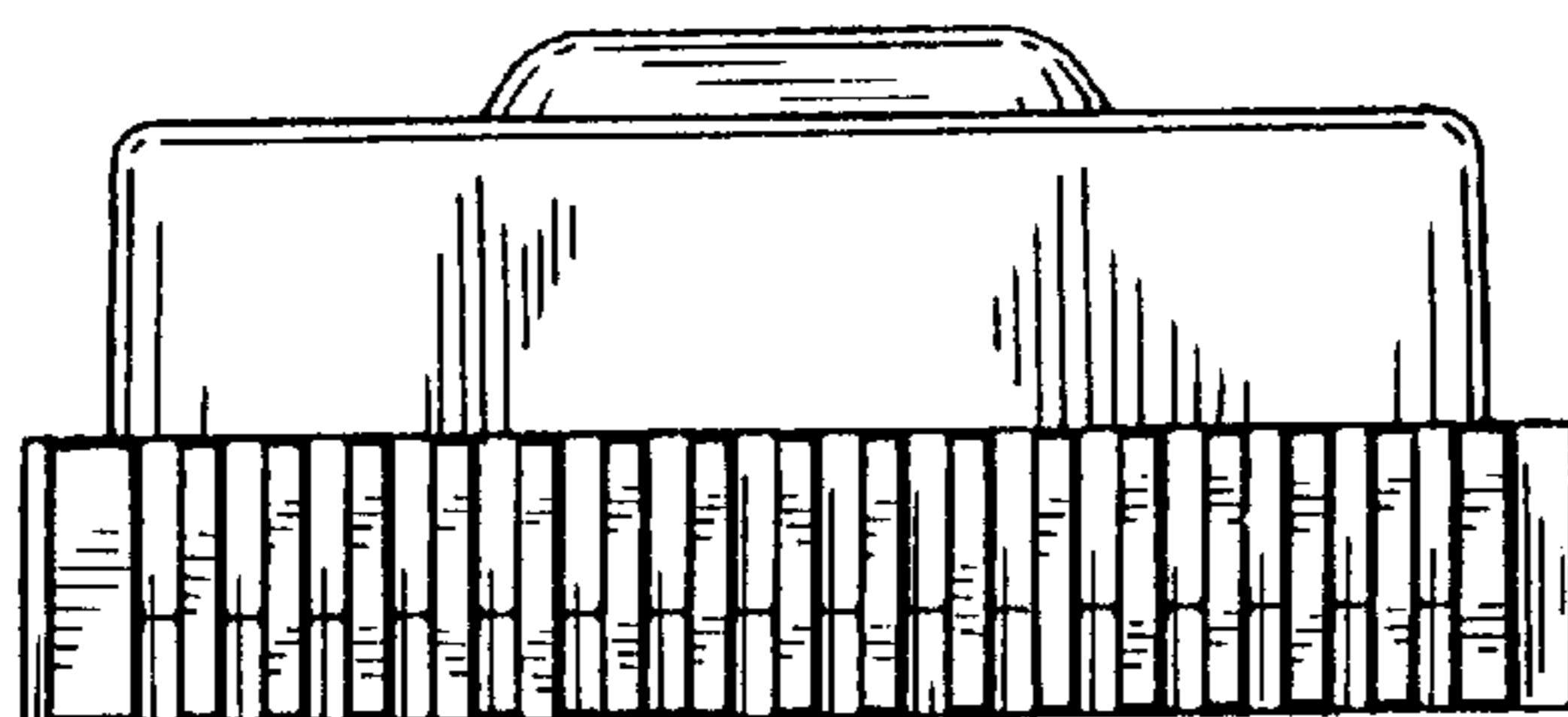


FIG. 14

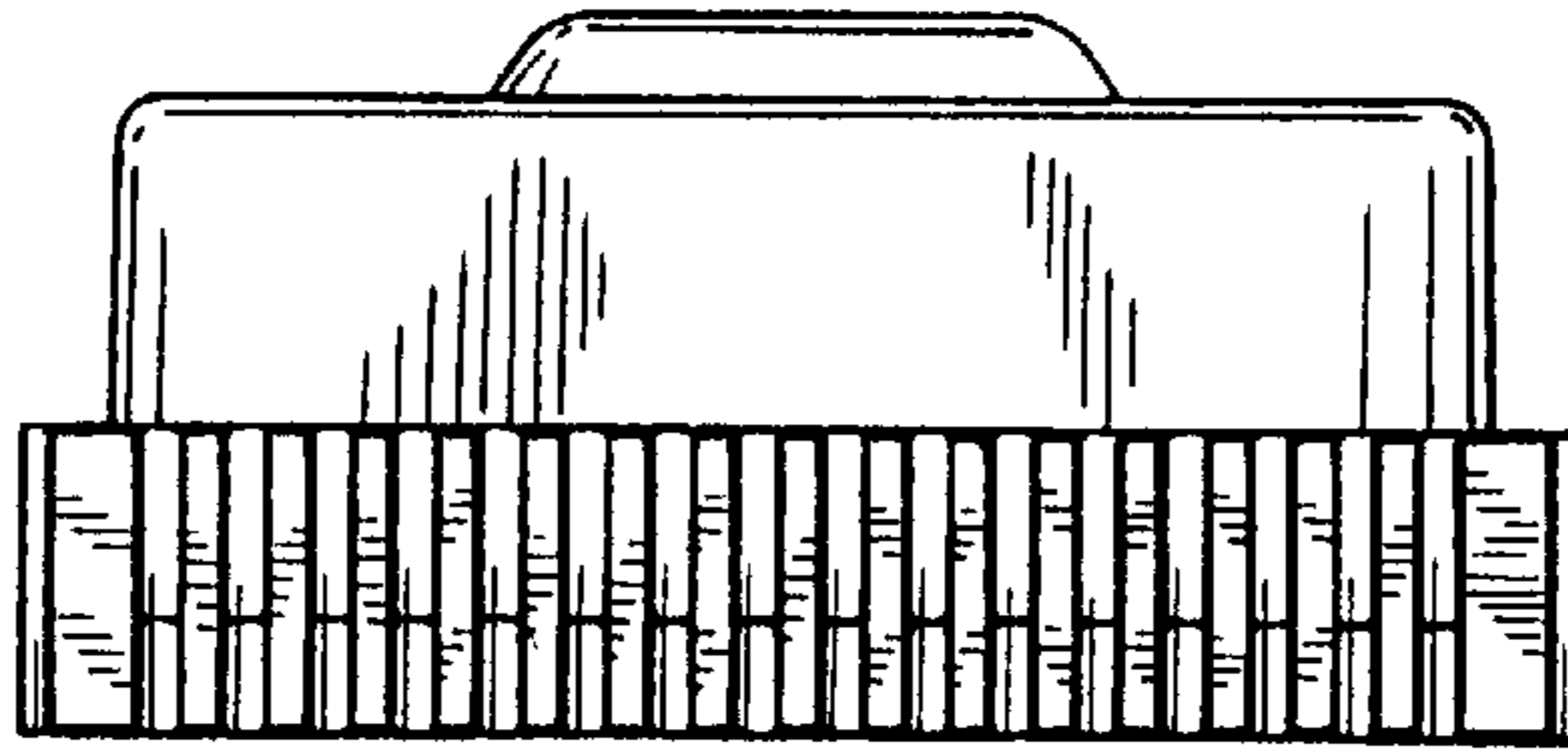


FIG. 18

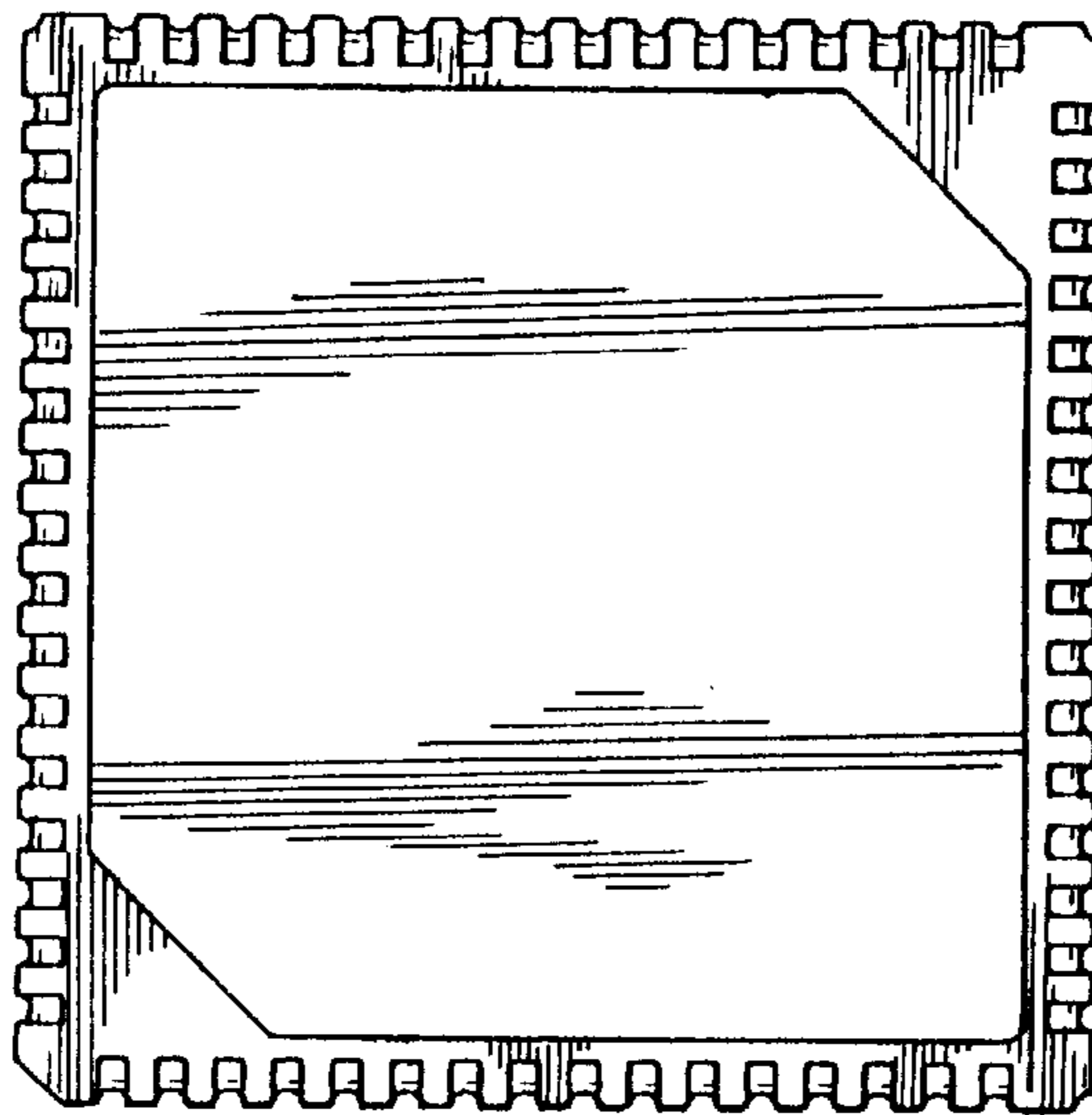


FIG. 17

